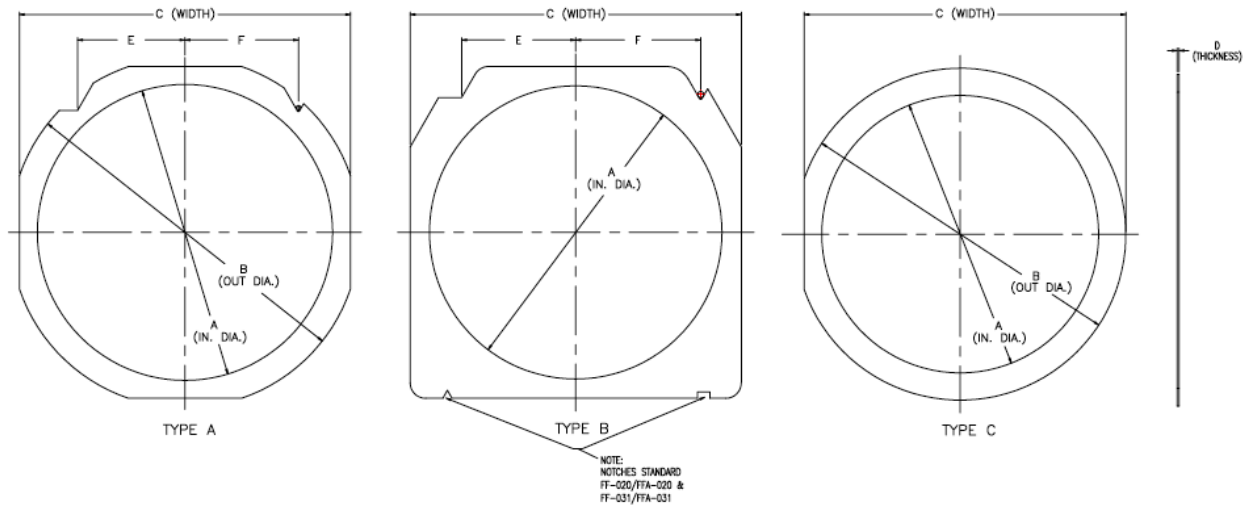


Wafer frame are used for dicing application, to hold the wafer during dicing.
It will be placed in a mounting tape machine, and the tape will be laminated on the wafer and the frame.
The assembly will be placed in a dicing machine and the wafer will be diced without die jump.

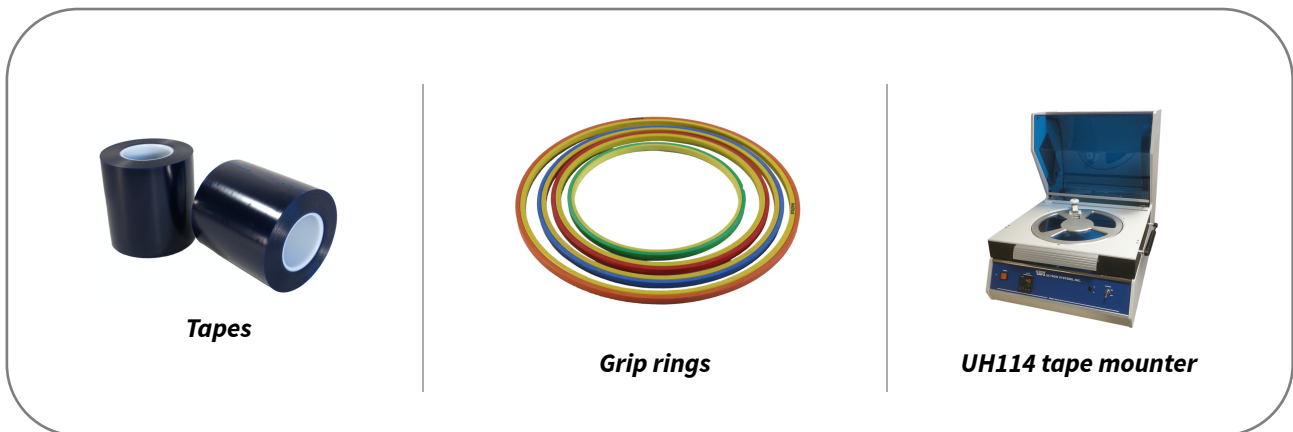


Dimensions



Wafer diameter	Frame style	Inside diameter mm (A)	Outside diameter mm (B)	Width mm (C)	Thickness mm (D)	Pin loc. (E)	Pin loc. (F)	Part number
4" - 100 mm	Type B	130.30	-	152.4	0.76	60.32	63.5	FF020
5" - 125 mm	Type A	165.1	196.85	184.15	1.01	60.45	63.5	FF045
6" - 150 mm	Type A	194	227.99	211.98	1.22	60.19	63.5	FF070
6" - 150 mm	Type A	192.53	228.09	215.9	1.22	70	73.96	FF080
8" - 200 mm	Type A	249.98	295.98	275.99	1.22	60.47	63.5	FF108
12" - 300 mm	Type A	349.98	399.99	379.98	1.52	86	76.2	FF123

Material: Stainless steel



Tapes

Grip rings

UH114 tape mounter